Preferred Device

# **Dual Schottky Barrier Diodes**

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

#### **Features**

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 V @ I<sub>F</sub> = 10 mAdc
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	30	V
Forward Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>F</sub>	150 1.2	mW mW/°C
Forward Current (DC)	I <sub>F</sub>	200 Max	mA
Junction Temperature	TJ	125 Max	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

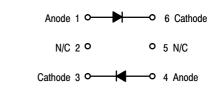
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

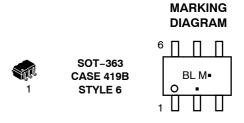


#### ON Semiconductor®

http://onsemi.com

# 30 VOLTS DUAL HOT-CARRIER DETECTOR AND SWITCHING DIODES





M = Date Code ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

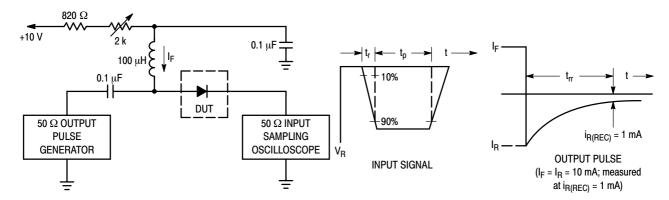
Device	Package	Shipping <sup>†</sup>		
MBD54DWT1G	SOT-363 (Pb-Free)	3000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted) (EACH DIODE)

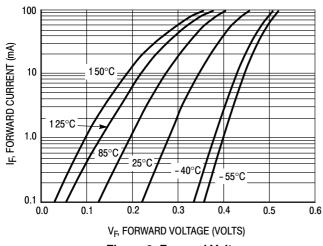
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μA)	V <sub>(BR)R</sub>	30	-	-	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	C <sub>T</sub>	-	7.6	10	pF
Reverse Leakage (V <sub>R</sub> = 25 V)	I <sub>R</sub>	-	0.5	2.0	μAdc
Forward Voltage (I <sub>F</sub> = 0.1 mAdc)	V <sub>F</sub>	-	0.22	0.24	Vdc
Forward Voltage (I <sub>F</sub> = 30 mAdc)	V <sub>F</sub>	-	0.41	0.5	Vdc
Forward Voltage (I <sub>F</sub> = 100 mAdc)	V <sub>F</sub>	-	0.52	1.0	Vdc
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mAdc}$ , $I_{R(REC)} = 1.0 \text{ mAdc}$ ) (Figure 1)	t <sub>rr</sub>	-	_	5.0	ns
Forward Voltage (I <sub>F</sub> = 1.0 mAdc)	V <sub>F</sub>	-	0.29	0.32	Vdc
Forward Voltage (I <sub>F</sub> = 10 mAdc)	V <sub>F</sub>	-	0.35	0.40	Vdc
Forward Current (DC)	I <sub>F</sub>	-	-	200	mAdc
Repetitive Peak Forward Current	I <sub>FRM</sub>	-	-	300	mAdc
Non-Repetitive Peak Forward Current (t < 1.0 s)	I <sub>FSM</sub>	-	-	600	mAdc



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (IF) of 10 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.
- 3.  $t_p * t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit



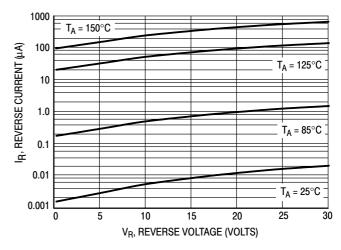


Figure 2. Forward Voltage

Figure 3. Leakage Current

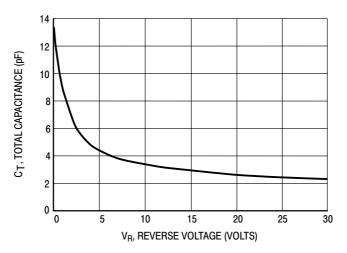
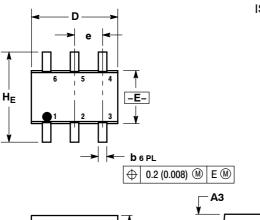
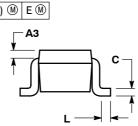


Figure 4. Total Capacitance

#### PACKAGE DIMENSIONS

#### SC-88 (SOT-363) CASE 419B-02 ISSUF W





#### NOTES

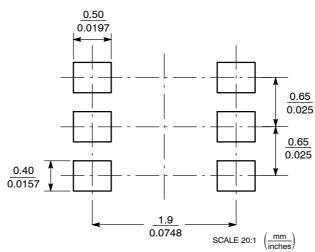
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
А3	0.20 REF			0.008 REF			
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65 BSC			0.026 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

#### STYLE 6: PIN 1. ANODE 2

- 2 N/C
- 3. CATHODE 1 4. ANODE 1
- N/C
- 6. CATHODE 2

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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